Wire Sawing Application Sheet - General

Company :			*Technical advise*	☐
Address :			*Quote*	☐
			Order	☐
			Claim	☐

Please provide below detailed information about intended sclicing operation

1	**1. Machine & Wafer**	
1.1	Type & model	
1.2	Single / multi wire	
1.3	Supply traverser(s) [yes/no]	
1.4	Workpiece material	
1.5	Material size / dimensions [mm]	
1.6	Wafer thickness [µm]	
1.7	Mounting procedure	
2	**2. Wire**	
2.1	Core diameter [µm]	
2.2	Grit size & type [µm]	
2.3	Total wire width [µm]	
2.4	Wire field width / no of wires [mm]	
3	**3. Pulleys**	
3.1	No of return pulleys	
3.2	Diameter [mm]	
3.3	Material	
3.4	Shape of grooves	
3.5	No of guide pulleys	
3.6	Diameter [mm]	
3.7	Material	
3.8	Shape of grooves	
4	**4. Process**	
4.1	Wire tension [N]	
4.2	Wire speed [m/s]	
4.3	Wire run method [e.g. incremental]	
4.4	Total wire length [m]	
4.5	Wire reverse length [m]	
4.6	Introduce bow [mm]	
4.7	Feed rate 1 [mm/min]	
4.9	Feed rate 2 [mm/min]	
5.1	Feed rate 3 [mm/min]	
5.2	Rocking angle [°]	
5.3	Rocking speed [°/s]	
5.4	End of cut dwell [h/mm/ss]	
5	**5. Cooling & Cleaning**	
5.1	Coolant medium	
5.2	Coolant ratio	
5.3	Coolant flow [l/h or cc/min]	
5.4	Coolant temperature [°C]	